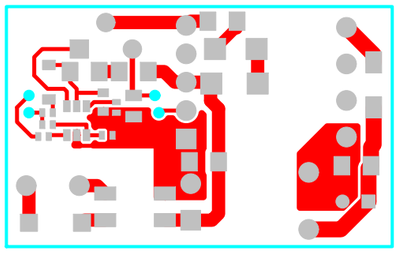
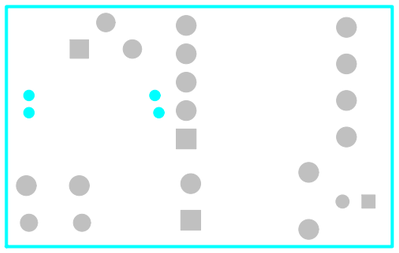
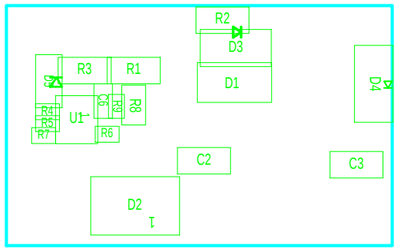


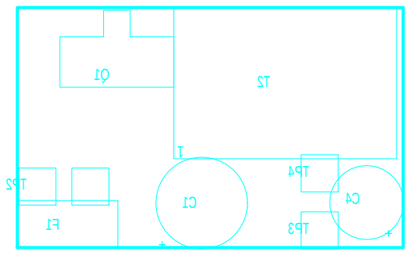
TEXAS INSTRUMENTS		Copper	Silkscreen		S Mask	Assembly		Fab Drawing
		Top Side	Top	Bot	Top	Top	Bot	
Board No. PMP8764	Rev. A	L1						
Date: 11-27-2012	Filename: PMP8764_REVA.PCB	Engineer: B King	PCB Dsgnr: B King		Modified Date: 11-27-2012			Software PADs v9.3



TEXAS INSTRUMENTS		Copper	Silkscreen		S Mask	Assembly		Fab Drawing
		Top Side	Top	Bot	Top	Top	Bot	
Board No. PMP8764	Rev. A							
Date: 11-27-2012	Filename: PMP8764_REVA.PCB	Engineer: B King	PCB Dsgnr: B King		Modified Date: 11-27-2012			Software PADs v9.3



TEXAS INSTRUMENTS		Copper	Silkscreen		S Mask	Assembly		Fab Drawing
		Top Side	Top	Bot	Top	Top	Bot	
Board No. PMP8764	Rev. A	L1				TA		
Date: 11-27-2012	Filename: PMP8764_REVA.PCB	Engineer: B King	PCB Dsgnr: B King		Modified Date: 11-27-2012			Software PADs v9.3



TEXAS INSTRUMENTS		Copper	Silkscreen		S Mask	Assembly		Fab Drawing
		Top Side	Top	Bot	Top	Top	Bot	
Board No. PMP8764	Rev. A						BA	
Date: 11-27-2012	Filename: PMP8764_REVA.PCB	Engineer: B King	PCB Dsgnr: B King		Modified Date: 11-27-2012			Software PADs v9.3

FABRICATION CHART

FINISHED THICKNESS	SILKSCREEN	SOLDERMASK	FINISHED COPPER WEIGHT
☐ 0.031	■ LAYER 1	■ LAYER 1	☐ 1 OZ.
■ 0.062	■ LAYER 2	☐ LAYER 2	■ 2 OZ.
☐ 0.093	☐ NONE	☐ NONE	☐ OTHER _____
☐ 0.125			

DESIGN	TRACE/GAP SPACING	LAYER COUNT
☐ SMD	■ 0.010/0.010	■ SINGLE SIDED
☐ THRU-HOLE	☐ 0.008/0.007	☐ 2 LAYER
■ MIX	☐ 0.006/0.006	☐ 4 LAYER
		☐ OTHER _____

NOTES: UNLESS OTHERWISE SPECIFIED

1. MATERIAL: ALL MATERIALS, INCLUDING BUT NOT LIMITED TO BASE LAMINATE, BONDING MATERIALS AND SOLDERMASK COATINGS FORMING THE FINISHED PRINTED CIRCUIT BOARD SHALL MEET UL-796 REQUIREMENTS AND BE RoHS COMPLIANT AND HAVE A FLAMMABILITY OF UL94V-0.

2. BASE LAMINATE: PLASTIC SHEET, LAMINATED METAL CLAD, BASE MATERIAL NEMA TYPE FR-4 OR EQUIVALENT, W/Tg = 180 Deg C OR HIGHER. MINIMUM DECOMPOSITION TEMP (Td) OF 340 Deg C. GLASS EPOXY RESIN, COPPER-CLAD IN ACCORDANCE WITH FAB CHART OR STACKUP DETAIL, COMPLIANT WITH LEAD FREE PROCESS.

3. SOLDERMASK: SOLDERMASK OVER BARE COPPER (SMOBC) USING LIQUID PHOTO-IMAGEABLE SOLDERMASK IN ACCORDANCE WITH IPC-SM-840. COLOR: GREEN. MINOR SOLDERMASK ADJUSTMENTS TO FACILITATE PCB FAB OR ASSEMBLY ARE ALLOWED PROVIDED NO DEFECTS ARE CREATED AS A RESULT.

4. PLATING: NO PLATING IN HOLES REQUIRED.

5. FINISH: PLATE WITH RoHS COMPLIANT, IMMERSION SILVER PREFERRED, IMMERSION GOLD or TIN OR Sn/Ag/Cu, WITH RMA FLUX, 0.0005" +/- 0.0003" THICK MIN ALL EXPOSED AREAS AS COATED, NO ACTIVE FLUXES ARE ACCEPTABLE.

6. LEGEND: IF REQUIRED, SILKSCREEN LEGEND(S) WITH WHITE NON-CONDUCTIVE EPOXY INK.

7. MARKINGS: BOARD MUST BEAR VENDOR'S IDENTIFICATION CODE (ETCH OR WHITE NON-CONDUCTIVE INK). LOCATION OPTIONAL.

8. WORKMANSHIP: BOARD IS TO BE MANUFACTURED PER IPC-A-600 CLASS 2 REQUIREMENTS OR BETTER.

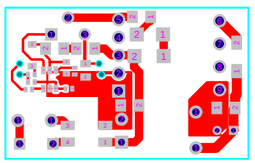
9. DOCUMENTATION: PCB VENDOR IS REQUIRED TO RETURN ANY AND ALL DOCUMENTS SUPPLIED OR ULTIMATELY PURCHASED BY TEXAS INSTRUMENTS UPON COMPLETION OF PURCHASE ORDER.

10. DRILL SIZES: HOLE DIAMETERS SHOWN ARE FINISHED SIZES AFTER PLATING UNLESS OTHERWISE NOTED.

11. TOLERANCES: UNLESS OTHERWISE SPECIFIED PCB TOLERANCES SHALL BE:
PCB THICKNESS TOLERANCE = +/- 10% RELATIVE TO FINISHED THICKNESS, MEASURED FROM COPPER TO COPPER.
PCB DIMENSIONAL TOLERANCE = +/-.005 INCHES RELATIVE TO BOARD PROFILE AND DRILL TO EDGE DIMENSIONS.
FINISHED HOLE DIAMETERS SHALL BE +/-.003 INCHES RELATIVE THE DRILL TABLE DIMENSIONS.

12. PANEL BORDER: ANY METAL IN BORDER AREA INCLUDING PART NUMBER, DATECODE AND/OR REVISION LETTERS MUST BE COVERED WITH SOLDERMASK.

13. PROCESS CHANGES: NO DIMENSIONAL, MATERIAL, OR PROCESS CHANGES ARE ALLOWED WITHOUT PRIOR EXPLICIT WRITTEN PERMISSION FROM TEXAS INSTRUMENTS.



TEXAS INSTRUMENTS		Copper	Silkscreen		S Mask	Assembly		Fab Drawing
		Top Side	Top	Bot	Top	Top	Bot	
Board No. PMP8764	Rev. A	L1						FB
Date: 11-27-2012	Filename: PMP8764_REVA.PCB	Engineer: B King	PCB Dsgnr: B King		Modified Date: 11-27-2012			Software: PADs v9.3

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